



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-06-14
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		


**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA25LY	ACWC*EAY25V2	A	ZS1A	2017-06-14
Amount		UoM	Unit type	ST ECOPACK Grade
8.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	2.9 - 2 - 1.175	3	gull wing	
Comment	Package: SOT 23 SIMPLE DIODE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	TRUE		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	FALSE		
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-12th January 2017				
Query	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ACWC*EAY2SV2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.330	mg	supplier	die	Silicon (Si)	7440-21-3		0.285	mg	863636	35625
				supplier	metallization	Aluminium (Al)	7429-90-5		0.039	mg	118182	4875
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	9091	375
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	3030	125
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	6061	250
Lead-frame	Copper & its alloys	2.338	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.257	mg	965355	282125
				supplier	alloy	Iron (Fe)	7439-89-6		0.053	mg	22669	6625
				supplier	alloy	Phosphorus (P)	12185-10-3		0.001	mg	428	125
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1283	375
				supplier	metallization	Silver (Ag)	7440-22-4		0.024	mg	10265	3000
Die attach	Other Organic Materials	0.029	mg	supplier	glue	Silver (Ag)	7440-22-4		0.025	mg	862069	3125
				supplier	glue	Carbocyclic Acrylates	proprietary		0.002	mg	68965	250
				supplier	glue	Bismaleimide resin	35325-39-4		0.001	mg	34483	125
				supplier	glue	2-preponoic acid, 2-methyl	68586-19-6		0.001	mg	34483	125
				supplier	wire	Gold (Au)	7440-57-5		0.030	mg	1000000	3750
Encapsulation	Other Organic Materials	5.074	mg	supplier	mold compound	Silica, vitreous	60676-86-0		4.328	mg	852976	541000
				supplier	mold compound	phenolic resin	29690-82-2		0.178	mg	35081	22250
				supplier	mold compound	epoxy resin	25068-38-6		0.203	mg	40008	25375
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.101	mg	19905	12625
				supplier	mold compound	carbon black	1333-86-4		0.010	mg	1971	1250
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.051	mg	10051	6375
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.203	mg	40008	25375
Connection coating	Solder	0.199	mg	supplier	solder	Tin (Sn)	7440-31-5		0.199	mg	1000000	24875